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(12) **United States Design Patent**  
**Fukumoto et al.**

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(45) **Date of Patent:** **\*\* Jul. 30, 2002**

(54) **SEMICONDUCTOR DEVICE**

6,300,685 B1 \* 10/2001 Hasegawa et al. .... 257/780

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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/144,818**

(22) Filed: **Jul. 12, 2001**

(30) **Foreign Application Priority Data**

Feb. 15, 2001 (JP) ..... 2001-003334

(51) **LOC (7) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Search** ..... D13/182; D14/114; 174/52.1, 52.2, 52.4, 52.5, 16.3; 206/710, 719; 257/254, 659, 697, 730, 738; 324/755, 765; 361/752, 798, 820, 718, 730

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(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and right side perspective view of a semiconductor device, showing our new design;

FIG. 2 is a front, bottom and right side perspective view thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a rear elevational view thereof;

FIG. 5 is a right side elevational view thereof; the left side elevational view is omitted as that is symmetrical to the right side elevational view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof; and,

FIG. 8 is a cross-sectional view thereof, taken along line 8—8 of FIG. 5, with the internal system omitted.

**1 Claim, 4 Drawing Sheets**

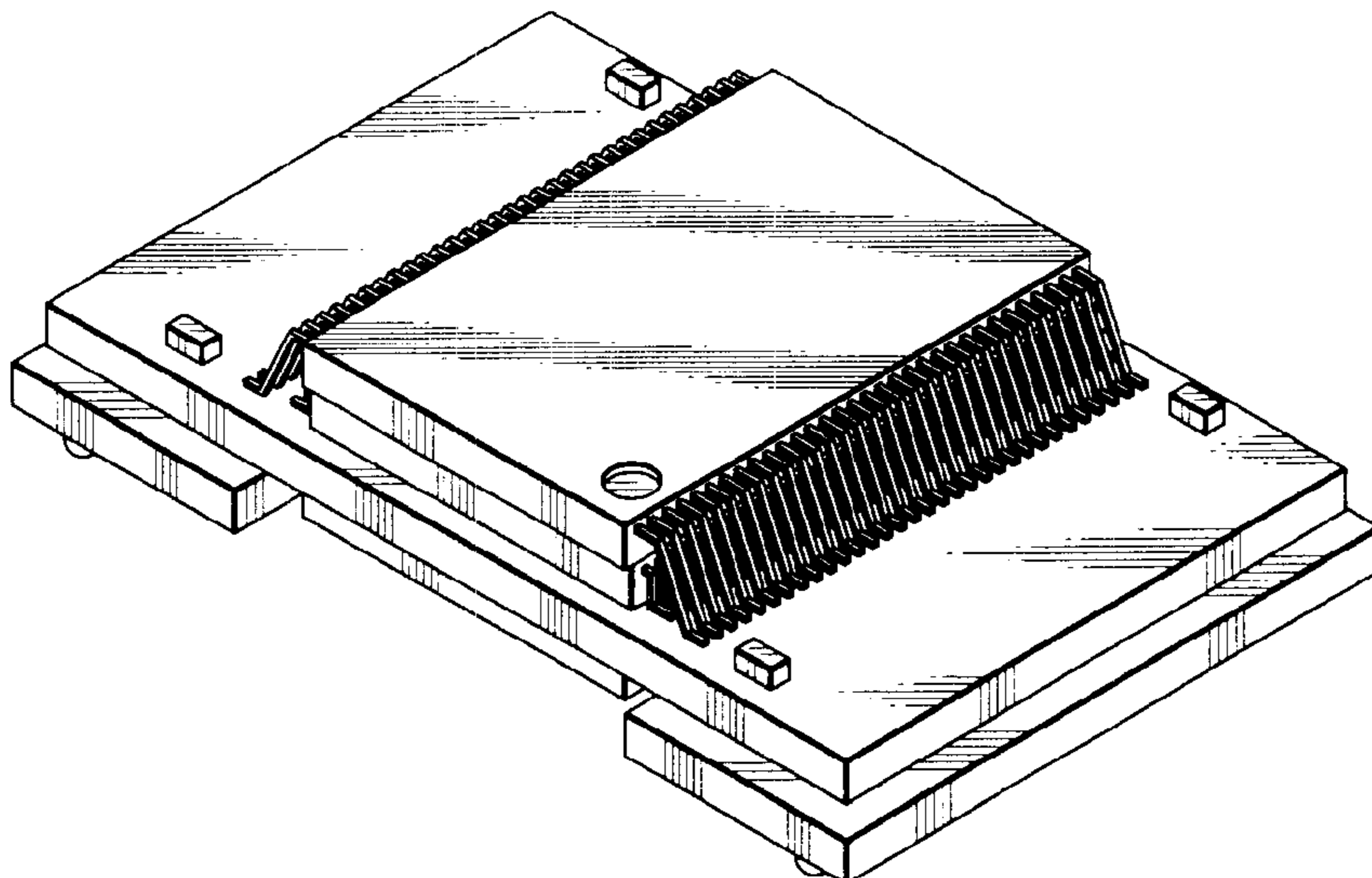


FIG. 1

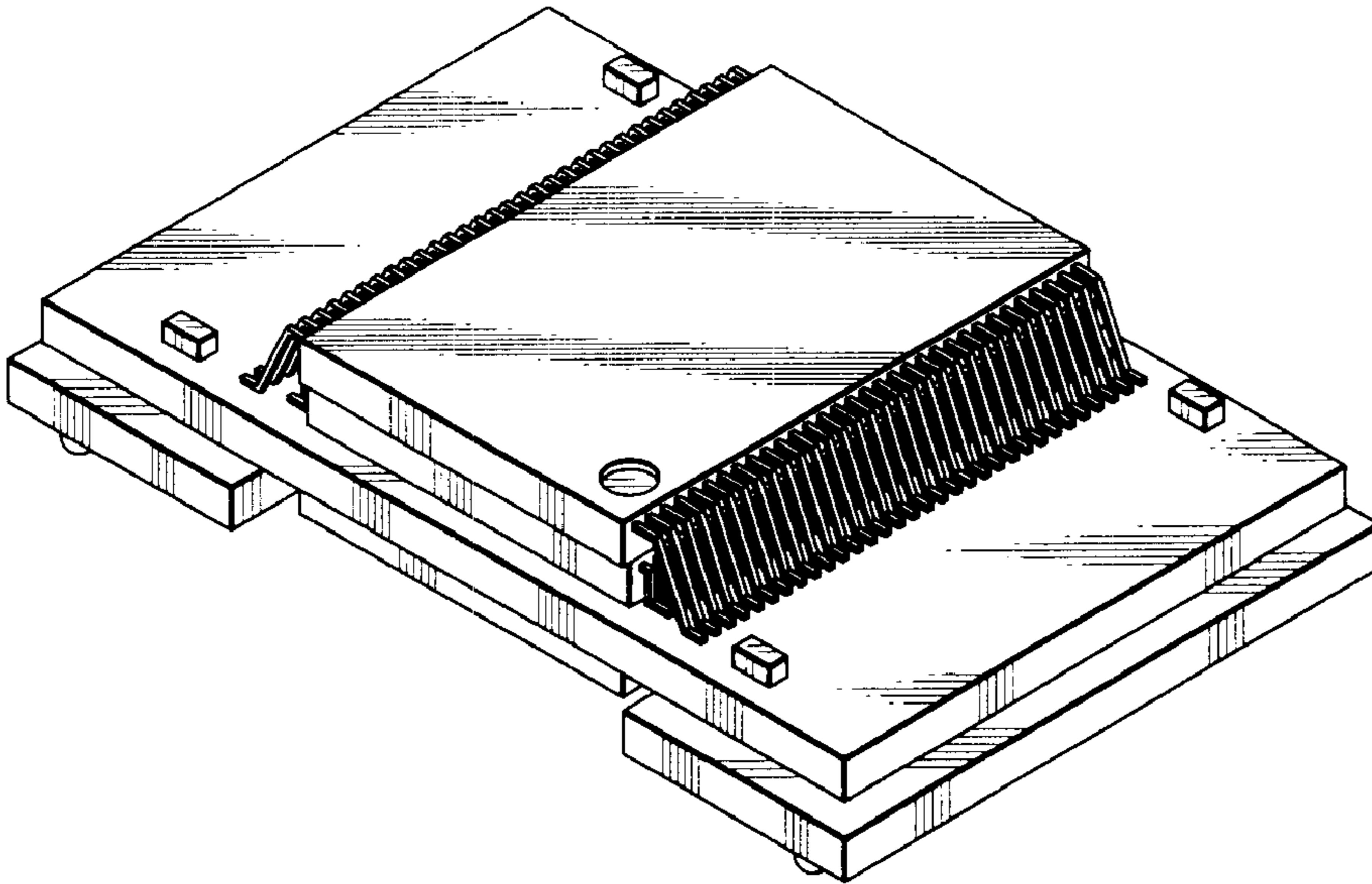


FIG. 2

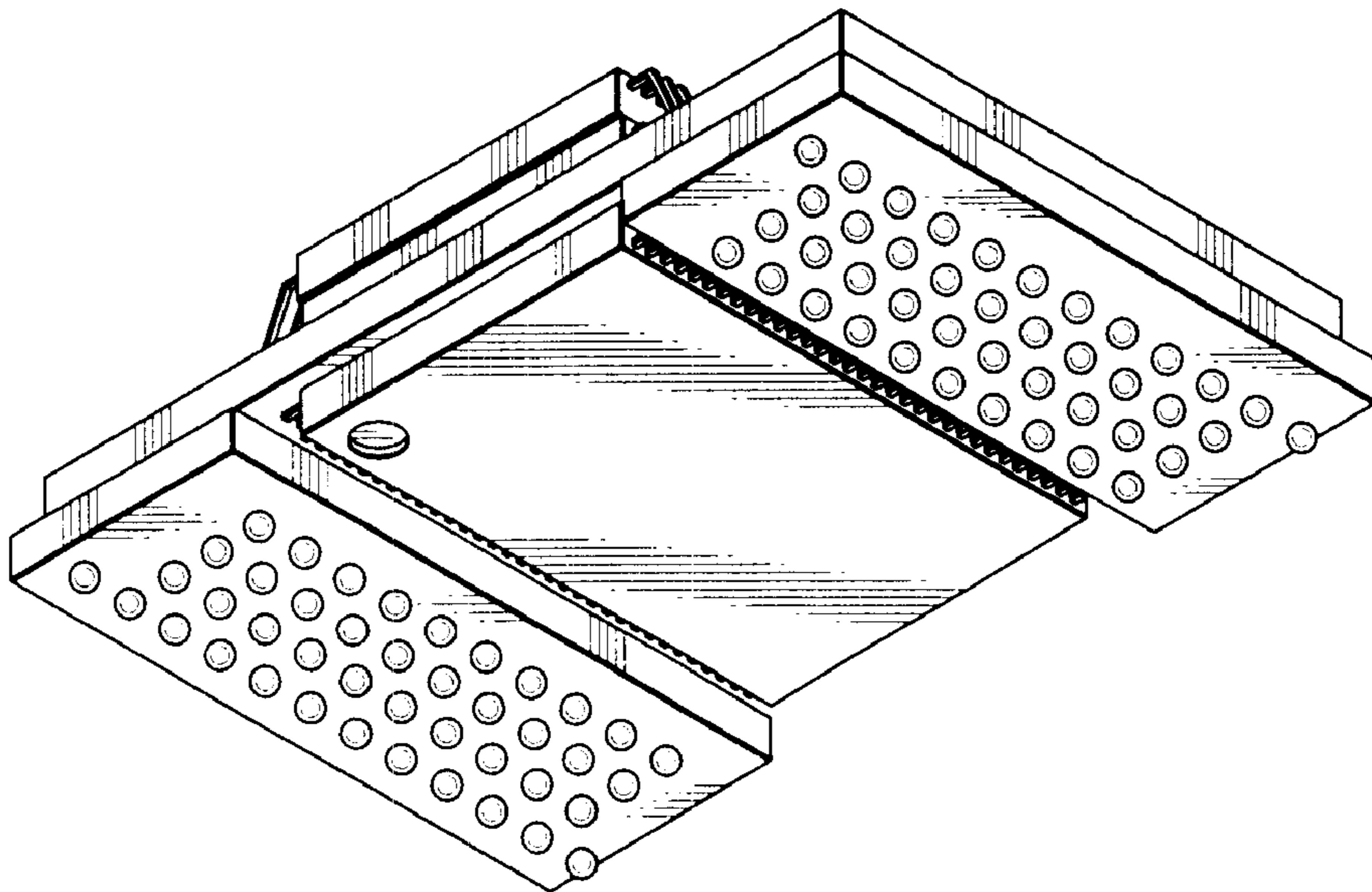


FIG. 3

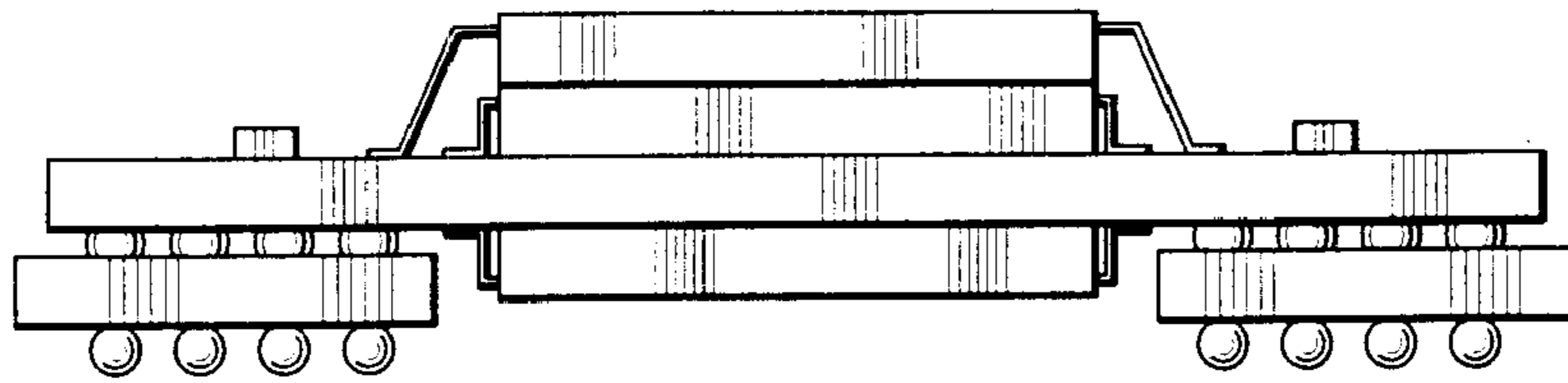


FIG. 4

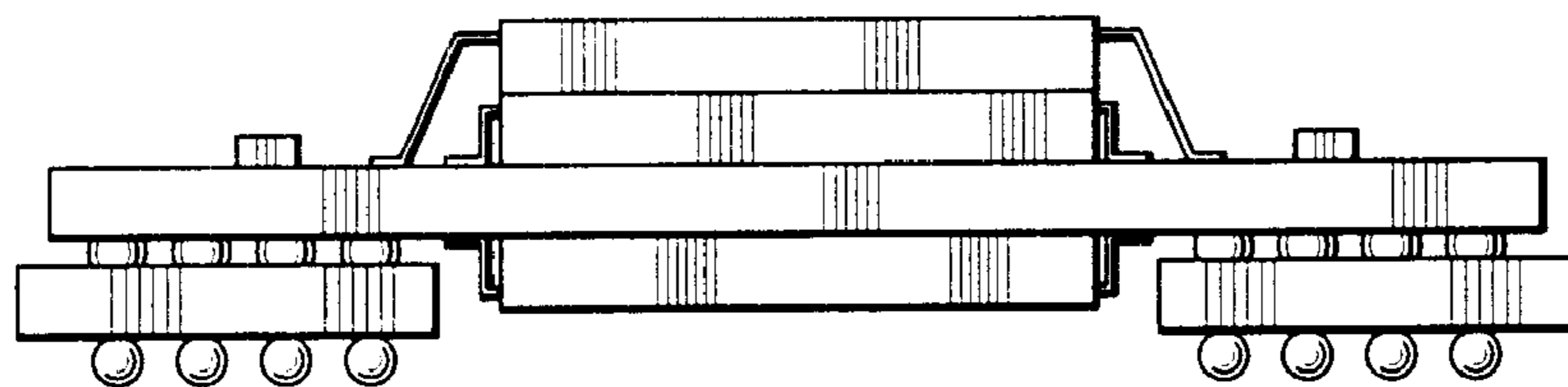


FIG. 5

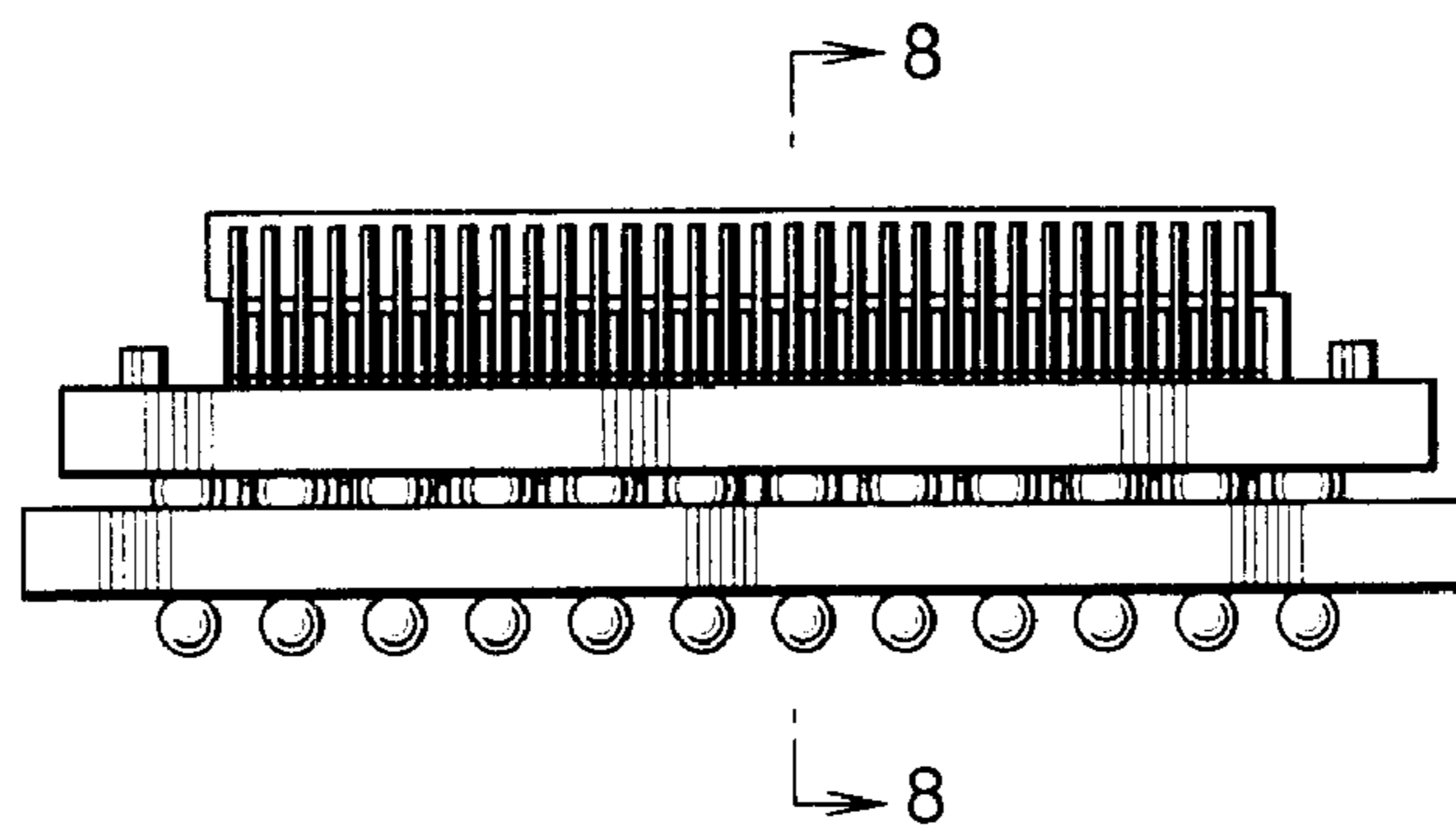


FIG. 6

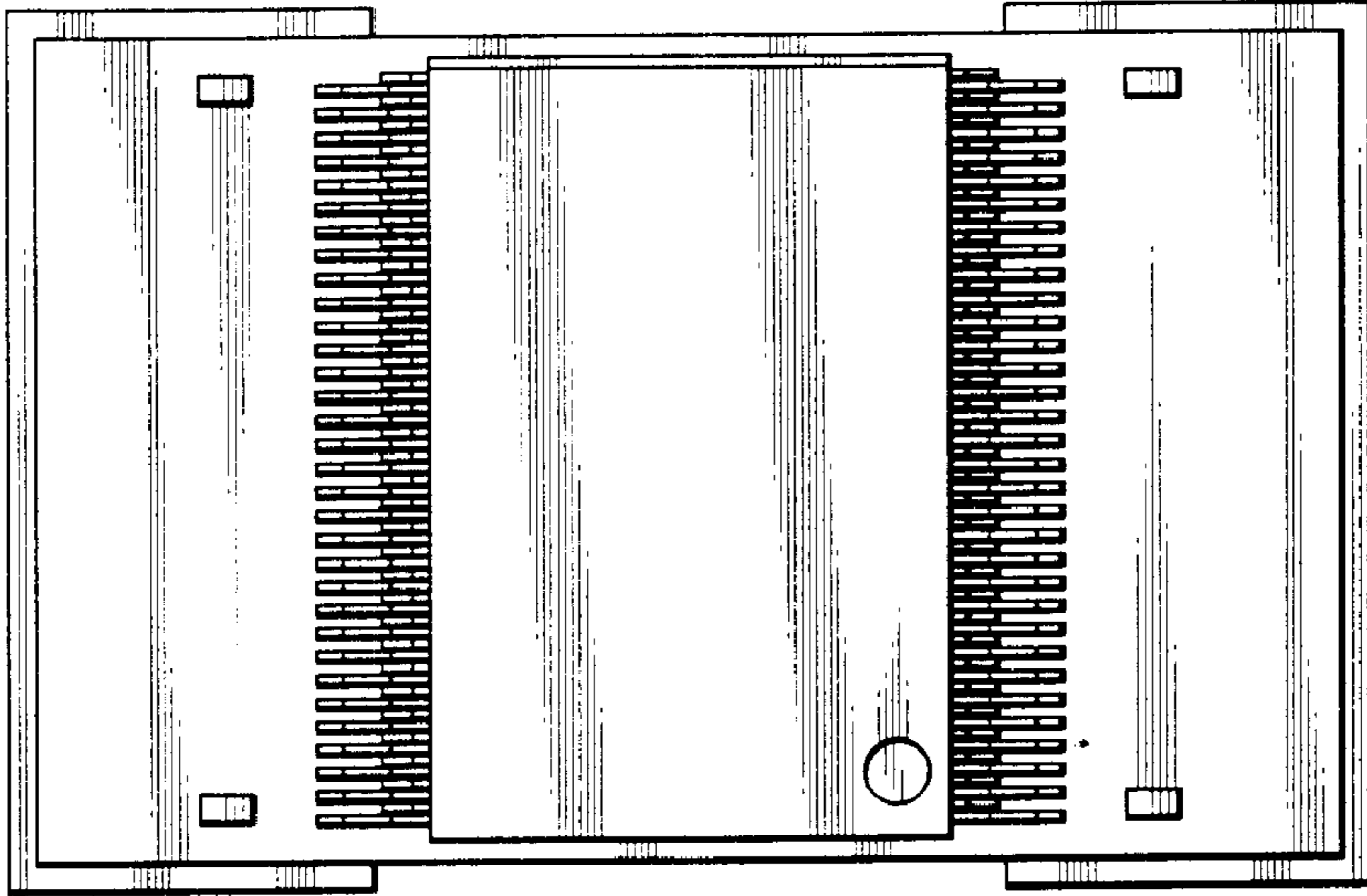


FIG. 7

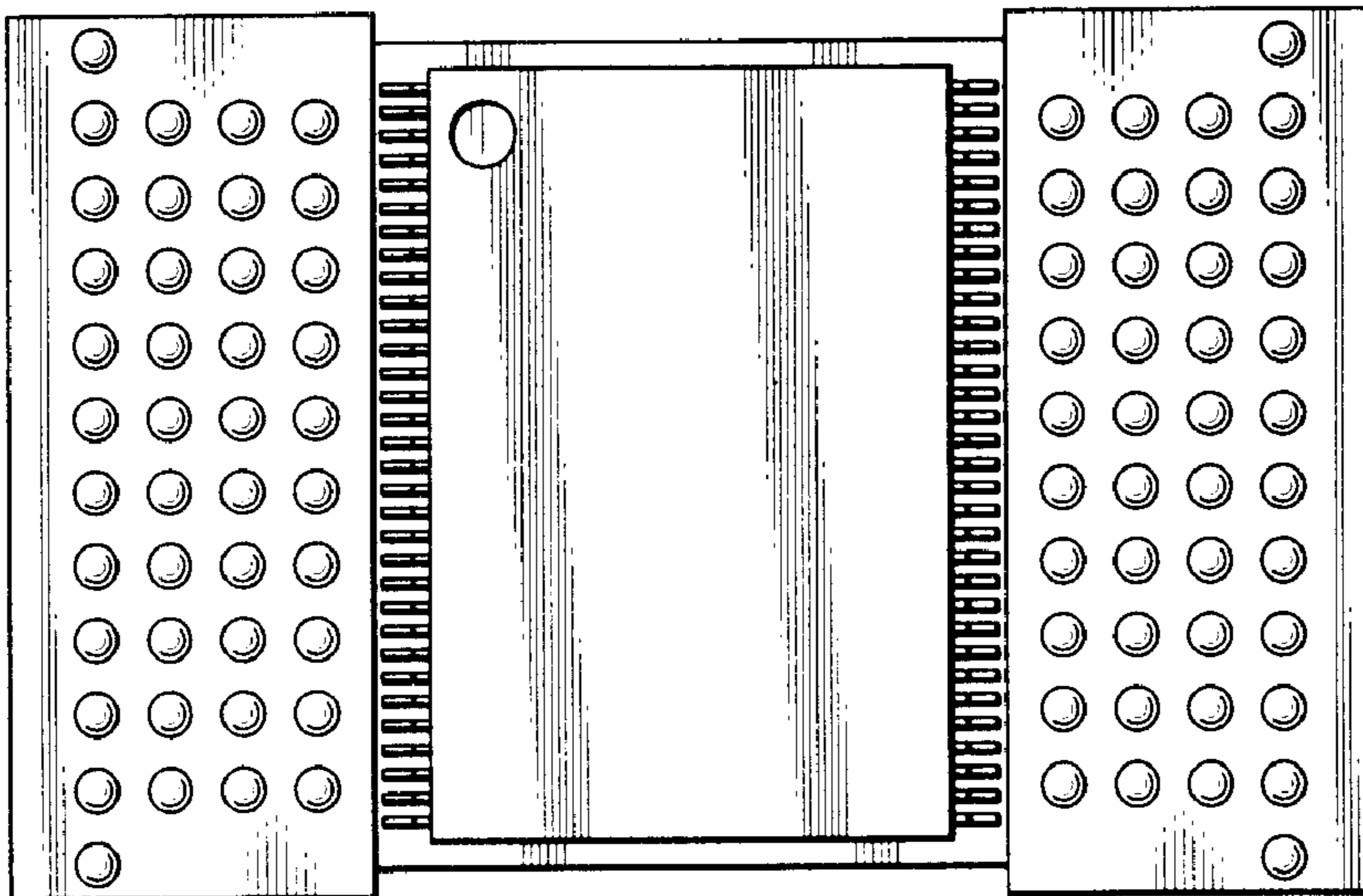


FIG. 8

